MOSPEC

SR3100

Schottky Barrier Rectifiers

Using the Schottky Barrier principle with a Refractory metal capable of high temperature operation metal. The proprietary barrier technology allows for reliable operation up to 150℃ junction temperature. Typical application are in switching Mode Power Supplies such as adaptors, DC/DC converters, free-wheeling and polarity protection diodes.

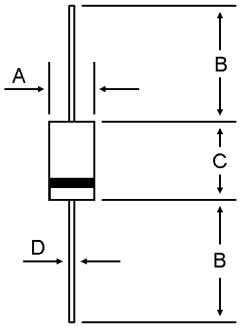
SCHOTTKY BARRIER RECTIFIERS

3.0 AMPERES
100 VOLTS

Features

- ∗Low Forward Voltage.
- ∗Low Switching noise.
- ∗High Current Capacity
- ∗Guarantee Reverse Avalanche.
- ∗Guard-Ring for Stress Protection.
- ∗Low Power Loss & High efficiency.
- ∗150℃ Operating Junction Temperature
- ∗Low Stored Charge Majority Carrier Conduction.
- ∗Plastic Material used Carries Underwriters Laboratory Flammability Classification 94V-O
- ∗Green product-halogen free

DO-201AD



DIM	MILLIMETERS	
	MIN	MAX
A	5.00	5.60
B	25.40	---
C	8.50	9.50
D	1.20	1.30

CASE---
Transfer molded plastic

POLARITY---
Cathode indicated polarity band

MAXIMUM RATINGS

Characteristic	Symbol	SR3100	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	100	V
RMS Reverse Voltage	$VR_{(RMS)}$	70	V
Average Rectifier Forward Current	I_O	3.0	A
Non-Repetitive Peak Surge Current (Surge applied at rate load conditions half-wave, single phase,60Hz)	I_{FSM}	75	A
Operating and Storage Junction Temperature Range	T_J , T_{STG}	-65 to +150	℃

THERMAL RESISTANCES

Typical Thermal Resistance junction to case	$R_{\theta jc}$	45	℃/w

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Maximum Instantaneous Forward Voltage (I_F =3 Amp T_C = 25℃) (I_F =3 Amp T_C = 125℃)	V_F	--- ---	0.75 0.60	0.85 ---	V
Maximum Instantaneous Reverse Current (Rated DC Voltage, T_C = 25℃) (Rated DC Voltage, T_C = 125℃)	I_R	--- ---	0.1 1	10 ---	uA mA
Typical Junction Capacitance (Reverse Voltage of 4 volts & f=1 MHz)	C_P		150		pF

FIG-1 FORWARD CURRENT DERATING CURVE

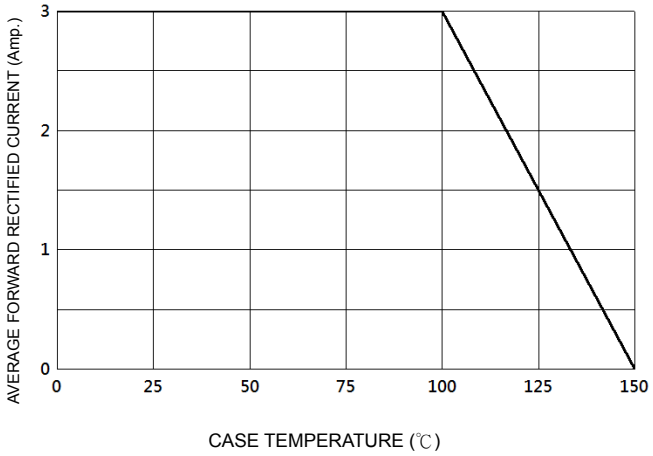


FIG-2 TYPICAL FORWARD CHARACTERISTICS

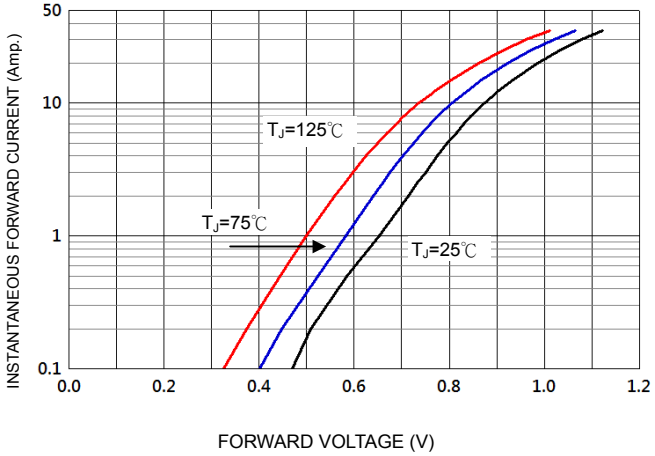


FIG-3 TYPICAL REVERSE CHARACTERISTICS

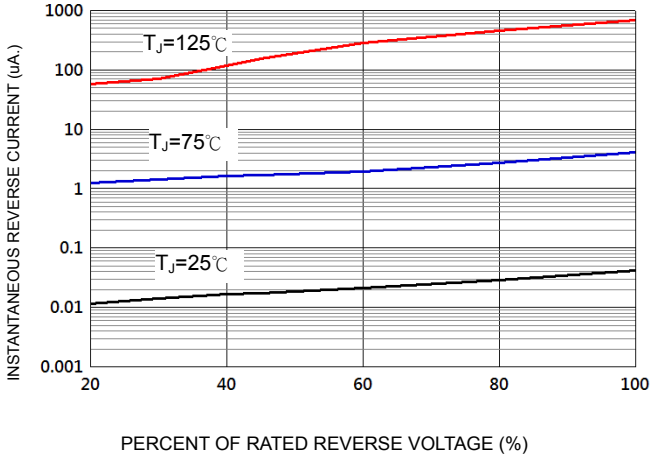


FIG-4 TYPICAL JUNCTION CAPACITANCE

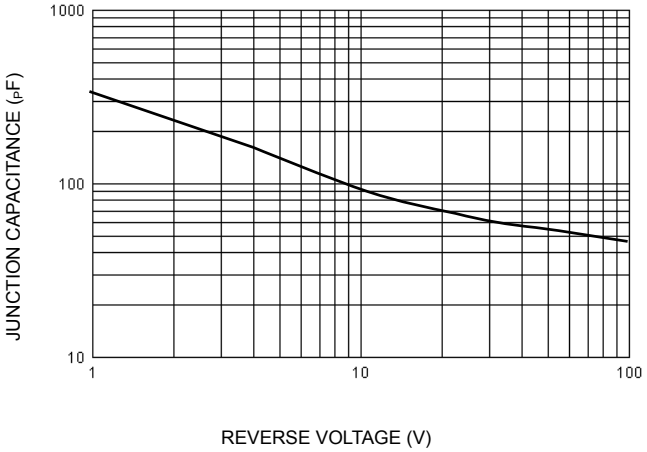
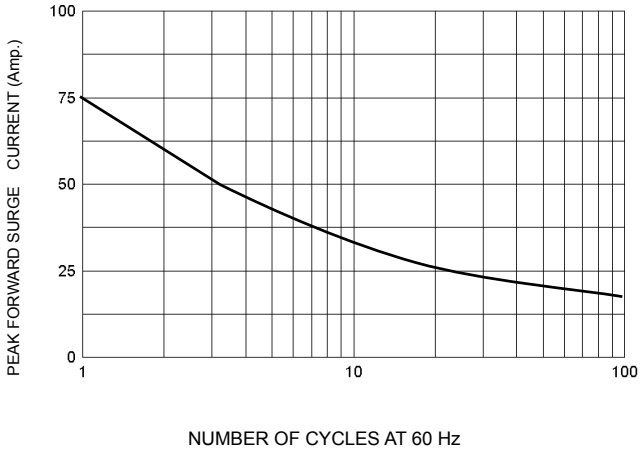


FIG-5 PEAK FORWARD SURGE CURRENT



PACKAGE:

OUTLINE	PACKING METHOD	PCS/BOX	PCS/CARTON
DO-201AD	TAPE PACKING	1250	12500

SOLDER_REFLOW_PROFILE

Table 4-2 Pb-free Process – Package Classification Reflow Temperatures

Package Thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6 mm	260 +0 °C *	260 +0 °C *	260 +0 °C *
1.6 mm - 2.5 mm	260 +0 °C *	250 +0 °C *	245 +0 °C *
≥2.5 mm	250 +0 °C *	245 +0 °C *	245 +0 °C *
* Tolerance: The device manufacturer/supplier **shall** assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0 °C. For example 260 °C+0°C) at the rated MSL level.			

Table 5-2 Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-Up Rate (Ts_{max} to Tp)	3 °C/second max.	3° C/second max.
Preheat – Temperature Min (Ts_{min}) – Temperature Max (Ts_{max}) – Time (ts_{min} to ts_{max})	100 °C 150 °C 60-120 seconds	150 °C 200 °C 60-180 seconds
Time maintained above: – Temperature (T_L) – Time (t_L)	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak/Classification Temperature (Tp)	See Table 4.1	See Table 4.2
Time within 5 °C of actual Peak Temperature (tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6 °C/second max.	6 °C/second max.
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

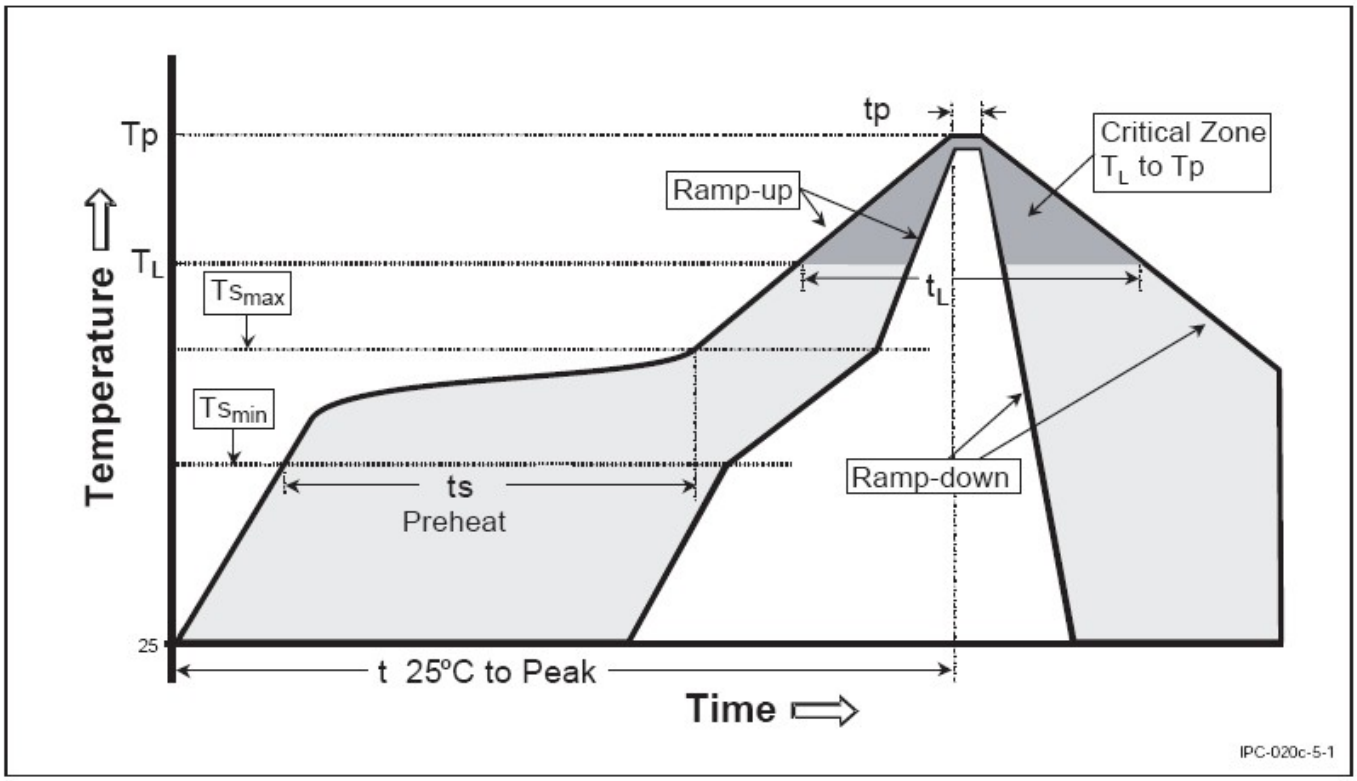


Figure 5-1 Classification Reflow Profile

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